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Front Matter: Volume 8973

, "Front Matter: Volume 8973," Proc. SPIE 8973, Micromachining and Microfabrication Process Technology XIX, 897301 (27 March 2014); doi: 10.1117/12.2064078

Event: SPIE MOEMS-MEMS, 2014, San Francisco, California, United States

PROCEEDINGS OF SPIE

Micromachining and Microfabrication Process Technology XIX

**Mary Ann Maher
Paul J. Resnick**
Editors

**4–6 February 2014
San Francisco, California, United States**

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Published by
SPIE

Volume 8973

Proceedings of SPIE 0277-786X, V. 8973

SPIE is an international society advancing an interdisciplinary approach to the science and application of light.

Micromachining and Microfabrication Process Technology XIX, edited by Mary Ann Maher, Paul J. Resnick,
Proc. of SPIE Vol. 8973, 897301 · © 2014 SPIE · CCC code: 0277-786X/14/\$18 · doi: 10.1117/12.2064078

Proc. of SPIE Vol. 8973 897301-1

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Author(s), "Title of Paper," in *Micromachining and Microfabrication Process Technology XIX*, edited by Mary Ann Maher, Paul J. Resnick, Proceedings of SPIE Vol. 8973 (SPIE, Bellingham, WA, 2014) Article CID Number.

ISSN: 0277-786X

ISBN: 9780819498861

Published by

SPIE

P.O. Box 10, Bellingham, Washington 98227-0010 USA

Telephone +1 360 676 3290 (Pacific Time) · Fax +1 360 647 1445

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